

42390.P955
PATENT & TRADEMARK OFFICE
U.S. DEPT. OF COMMERCE
OCT 9/4/01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Mu, et al.

Serial No.: 09/661,899

Filed: September 14, 2000

For: PROCESS FOR FORMING A
DIRECT BUILD-UP LAYER ON AN
ENCAPSULATED DIE PACKAGE
AND INTERMEDIATE
STRUCTURES FORMED
THEREWITH

Examiner: A. Chambliss

Group Art Unit: 2814

Attorney Docket No.: 42390.P8497

PATENT

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RESPONSE TO RESTRICTION REQUIREMENT
AND PRELIMINARY AMENDMENT

Hon. Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Restriction Requirement mailed August 3, 2001 and prior to the examination of the claims on the merits, Applicants respectfully request that the Examiner enter the following amendments: